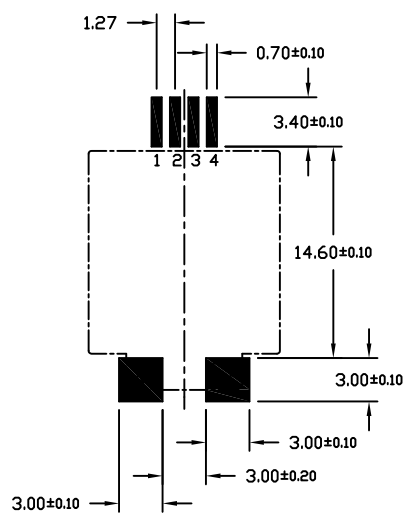
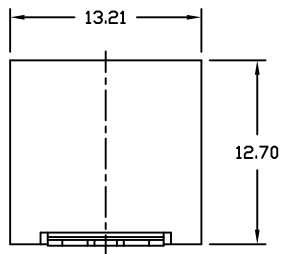
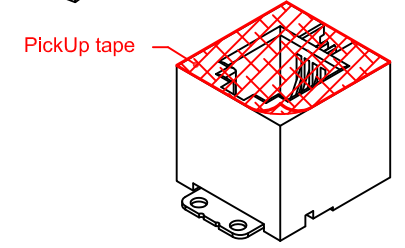
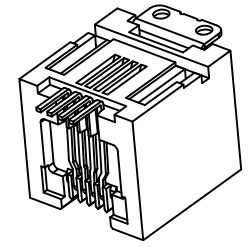
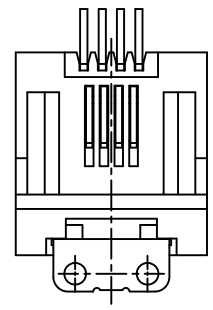
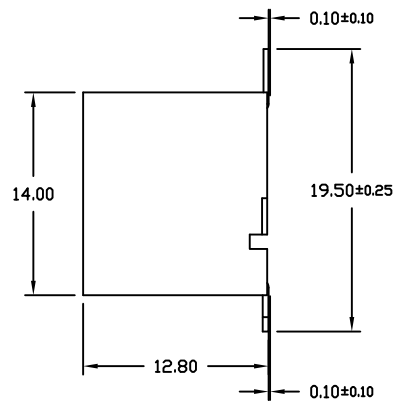
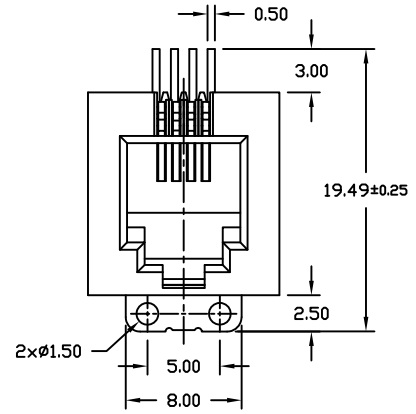


REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
A		RoHS	27.06.2006	John
B		P/N: -TSA03- -> -T1S0-	23.02.2009	Ronny
C		add pickup tape; PN add /R	18.02.2011	Ronny
D		New DWG. No.	01.02.2012	Ronny



RECOMMENDED PCB LAYOUT

NOTE :

- MATERIAL: HI TEMP THERMOPLASTIC UL94V-0
STANDARD COLOR-BLACK
CONTACT-PHOSPHOR BRONZE; 0.35mm THICK
SELECTIVE GOLD/TIN PLATED OVER Ni
HOLD DOWN: COPPER ALLOY; 0.40mm THICK
TIN OVER NICKEL
- ENVIROMENTAL:
OPERATING TEMPERATURE: -20°C TO +85°C
PROCESSING TEMPERATURE:
+230°C FOR 60 SEC. max.
+260°C -5/+0 FOR 5 SEC max.
- ELECTRICAL:
CURRANT RATING: 1,5A max. (@25°C)
VOLTAGE RATING: 150V AC max.
CONTACT RESISTANCE: 15mΩ max.
DIELECTRIC WITHSTANDING VOLTAGE:
1000V rms 1 MINUTE (60Hz)
INSULATION RESISTANCE:
500MΩ min.
- CAVITY CONFIRMS TO FCC RULES AND
REGISTRATION PAR68, SUBPARTS F.
- PACKING: REEL

PART NUMBER	GOLD PLATING CONTACT AREA
MJT-144-T1S0-96/R	6μ"
MJT-144-T1S0-97/R	15μ"
MJT-144-T1S0-98/R	30μ"
MJT-144-T1S0-9H/R	50μ"



UNIT	mm	GENERAL TOLERANCE		DRAWN	John	DATE	27.06.2006	DWG. NO.	1811100	SHEET 1/1
SCALE	Free	X.° ±	X. ±	CHECK	Ronny	DATE	01.02.2012	SERIES NO.	MJT-144-T1S0-xx/R	REV. D
		.XX° ±	.XX ±	APPROVE	Hogi	DATE	01.02.2012			
		ANG ± 0,5°	.XXX ±							

SMT PCB Jack RJ9 <4P4C>
Top Entry
NON Schielded